

STD20NF06 N-CHANNEL 60V - 0.032 Ω - 24A DPAK STripFET™ II POWER MOSFET

PRELIMINARY DATA

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| TYPE | V _{DSS} | R _{DS(on)} | ID | | | | |
|-----------|------------------|---------------------|------|--|--|--|--|
| STD20NF06 | 60 V | < 0.040 Ω | 24 A | | | | |
| | | | | | | | |

- TYPICAL $R_{DS}(on) = 0.032 \Omega$
- EXCEPTIONAL dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- APPLICATION ORIENTED CHARACTERIZATION
- SURFACE-MOUNTING DPAK (TO-252) POWER PACKAGE IN TAPE & REEL (SUFFIX "T4")

DESCRIPTION

This Power MOSFET is the latest development of STMicroelectronis unique "Single Feature Size™" stripbased process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

APPLICATIONS

- AUDIO AMPLIFIERS
- POWER TOOLS
- AUTOMOTIVE ENVIRONMENT

Ordering Information

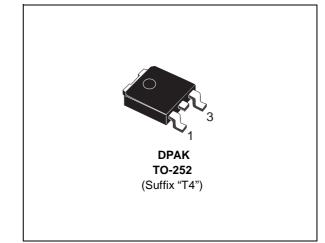
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|------------|-----------|---------|-------------|
| SALES TYPE | MARKING | PACKAGE | PACKAGING |
| STD20NF06 | STD20NF06 | TO-252 | TAPE & REEL |

ABSOLUTE MAXIMUM RATINGS

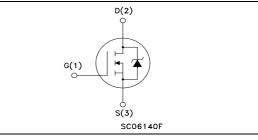
| Symbol | Parameter | Value | Unit |
|---------------------|--|---|---------------------|
| V _{DS} | Drain-source Voltage (V _{GS} = 0) | 60 | V |
| V _{DGR} | Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$) | 60 | V |
| V _{GS} | Gate- source Voltage | ± 20 | V |
| ID | Drain Current (continuous) at T _C = 25°C | 24 | A |
| ID | Drain Current (continuous) at T _C = 100°C | 17 | A |
| I _{DM} (●) | Drain Current (pulsed) | 96 | A |
| Ptot | Total Dissipation at $T_C = 25^{\circ}C$ | 60 | W |
| | Derating Factor | 0.4 | W/°C |
| dv/dt (1) | Peak Diode Recovery voltage slope | 10 | V/ns |
| E _{AS} (2) | Single Pulse Avalanche Energy | 300 | mJ |
| T _{stg} | Storage Temperature | -55 to 175 | °C |
| Тj | Operating Junction Temperature | -55 10 175 | |
| Pulse width | limited by safe operating area. | (1) I _{SD} ≤24A, di/dt ≤100A/µs, V _{DD} ≤ V _{(BR)DSS} , T _j : (2) Starting T _j = 25 °C, I _D =10 A, V _{DD} = 45V | ≤ T _{JMAX} |

May 2003

This is preliminary information on a new product now in development or undergoing evaluation. Details are subject to change without notice.



INTERNAL SCHEMATIC DIAGRAM



THERMAL DATA

| Rthj-amb T _l | Thermal Resistance Junction-case Thermal Resistance Junction-ambient Maximum Lead Temperature For Soldering Purpose (1.6 mm from case, for 10 sec) | Max Max | 2.5 100 275 | °C/W °C/W °C |
|----------------------------|---|------------|-------------------|--------------------|
|----------------------------|---|------------|-------------------|--------------------|

ELECTRICAL CHARACTERISTICS (T_{CASE} = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|-----------------------|--|---|------|------|---------|----------|
| V _(BR) DSS | Drain-source Breakdown Voltage | $I_D = 250 \ \mu A, \ V_{GS} = 0$ | 60 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current (V _{GS} = 0) | V_{DS} = Max Rating V_{DS} = Max Rating T _C = 125°C | | | 1 10 | μΑ μΑ |
| IGSS | Gate-body Leakage Current (V _{DS} = 0) | $V_{GS} = \pm 20V$ | | | ±100 | nA |

ON (*)

| Symbol | Parameter | Test Conditions | | Min. | Тур. | Max. | Unit |
|---------------------|--------------------------------------|------------------------|-------------------------|------|-------|-------|------|
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}$ | I _D = 250 μA | 2 | | 4 | V |
| R _{DS(on)} | Static Drain-source On Resistance | V _{GS} = 10 V | I _D = 12 A | | 0.032 | 0.040 | Ω |

DYNAMIC

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|--|--|-------------------------------------|------|------------------|------|----------------|
| g _{fs} (*) | Forward Transconductance | $V_{DS} = 25 V$ $I_D = 12 A$ | | 15 | | S |
| Ciss C _{oss} C _{rss} | Input Capacitance Output Capacitance Reverse Transfer Capacitance | $V_{DS} = 25V f = 1 MHz V_{GS} = 0$ | | 690 170 68 | | pF pF pF |

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|--------------------------------------|--|---|------|----------------|------|----------------|
| t _{d(on)} t _r | Turn-on Delay Time Rise Time | | | 10 30 | | ns ns |
| Qg Qgs Qgd | Total Gate Charge Gate-Source Charge Gate-Drain Charge | V _{DD} = 48 V I _D = 20 A V _{GS} = 10 V | | 23 5 7.5 | 31 | nC nC nC |

SWITCHING OFF

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|---------------------------------------|----------------------------------|--|------|---------|------|----------|
| t _{d(off)} t _f | Turn-off Delay Time Fall Time | $ \begin{array}{ll} V_{DD}=30 \ V & I_{D}=10 \ A \\ R_{G}=4.7 \Omega, & V_{GS}=10 \ V \\ (\text{Resistive Load, Figure 3}) \end{array} $ | | 30 8 | | ns ns |

SOURCE DRAIN DIODE

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|--|--|--|------|------------------|----------|---------------|
| I _{SD} I _{SDM} (●) | Source-drain Current Source-drain Current (pulsed) | | | | 24 96 | A A |
| V _{SD} (*) | Forward On Voltage | $I_{SD} = 96 \text{ A}$ $V_{GS} = 0$ | | | 1.5 | V |
| t _{rr} Q _{rr} I _{RRM} | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current | $\begin{split} I_{SD} &= 96 \text{ A} \qquad di/dt = 100 \\ V_{DD} &= 20 \text{ V} \qquad T_j = 150' \\ (\text{see test circuit, Figure 5}) \end{split}$ | | 65 150 4.6 | | ns nC A |

(*)Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

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Fig. 1: Unclamped Inductive Load Test Circuit

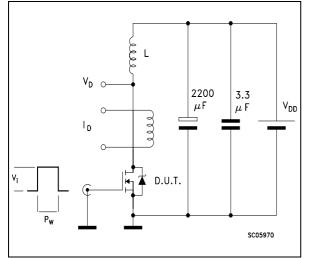


Fig. 3: Switching Times Test Circuits For Resistive Load

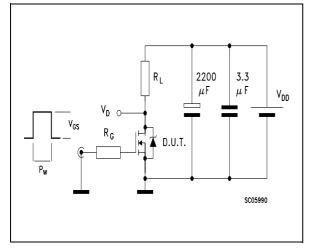


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

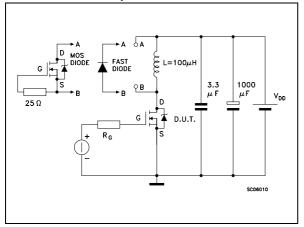


Fig. 2: Unclamped Inductive Waveform

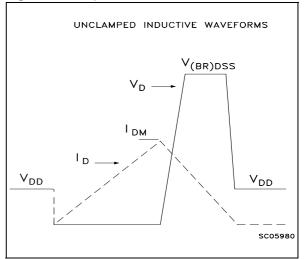
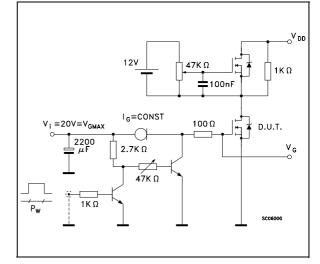


Fig. 4: Gate Charge test Circuit

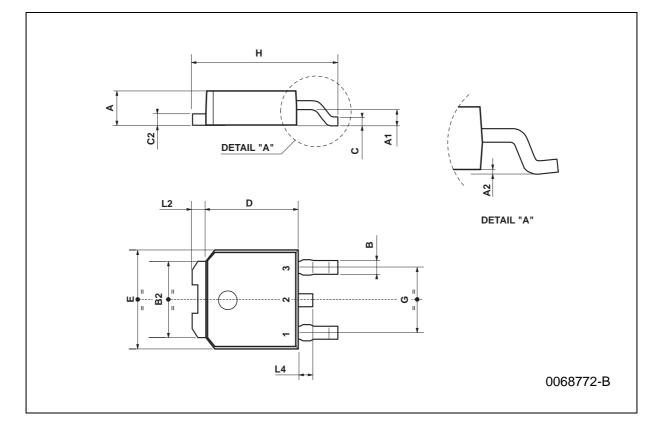


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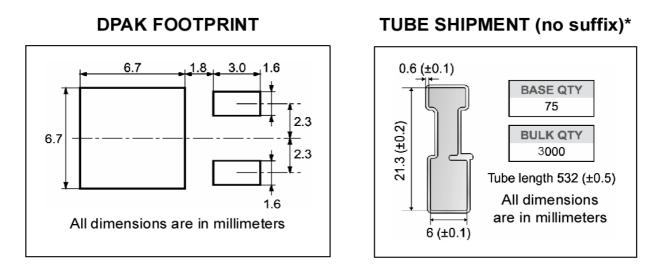
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| DIM. | | mm | | inch | | | |
|------|------|------|------|-------|-------|-------|--|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. | |
| А | 2.2 | | 2.4 | 0.086 | | 0.094 | |
| A1 | 0.9 | | 1.1 | 0.035 | | 0.043 | |
| A2 | 0.03 | | 0.23 | 0.001 | | 0.009 | |
| В | 0.64 | | 0.9 | 0.025 | | 0.035 | |
| B2 | 5.2 | | 5.4 | 0.204 | | 0.212 | |
| С | 0.45 | | 0.6 | 0.017 | | 0.023 | |
| C2 | 0.48 | | 0.6 | 0.019 | | 0.023 | |
| D | 6 | | 6.2 | 0.236 | | 0.244 | |
| Е | 6.4 | | 6.6 | 0.252 | | 0.260 | |
| G | 4.4 | | 4.6 | 0.173 | | 0.181 | |
| Н | 9.35 | | 10.1 | 0.368 | | 0.397 | |
| L2 | | 0.8 | | | 0.031 | | |
| L4 | 0.6 | | 1 | 0.023 | | 0.039 | |

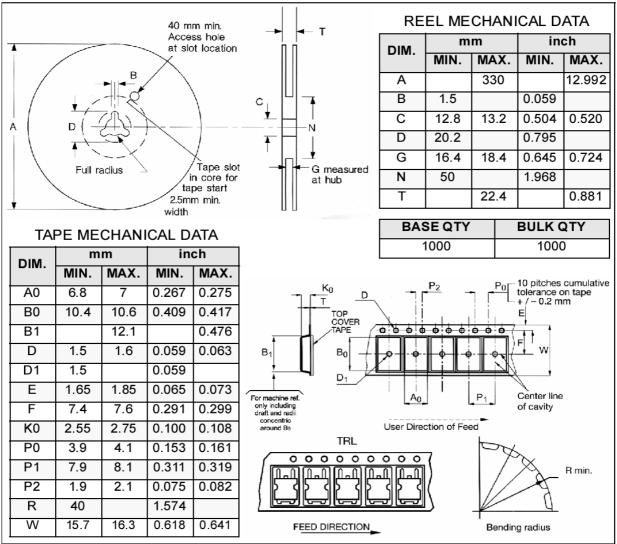




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TAPE AND REEL SHIPMENT (suffix "T4")*



*on sales type

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